

SUBMINIATURE SOLID STATE LAMP

Part Number: AM27SGD03 Super Bright Green

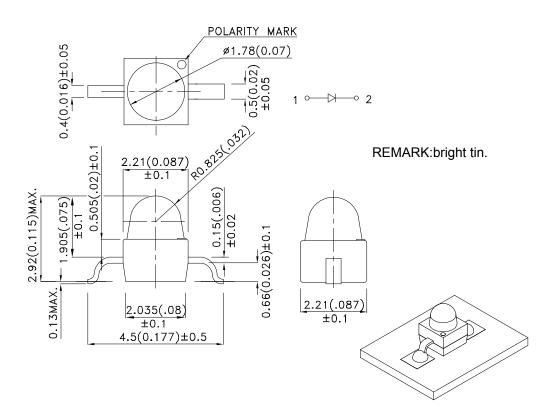
Features

- SUBMINIATURE PACKAGE.
- GULL WING.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE :1000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- RoHS COMPLIANT.

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Dice	lv (mcd) [2] Lens Type @ 20mA		,	Viewing Angle [1]
			Min.	Тур.	201/2
AM27SGD03	Super Bright Green (GaP)	GREEN DIFFUSED	2.6	10	40°

- Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	IF=20mA
lR	Reverse Current	Super Bright Green		10	uA	V _R =5V

Notes:

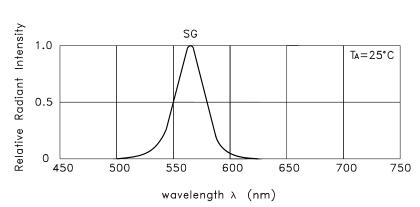
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Green	Units	
Power dissipation	62.5	mW	
DC Forward Current	25	mA	
Peak Forward Current [1]	140	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

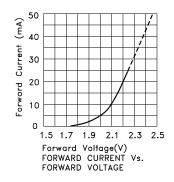
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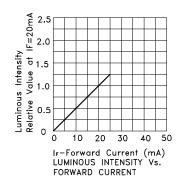


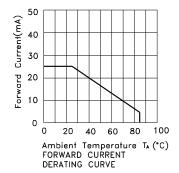
RELATIVE INTENSITY Vs. WAVELENGTH

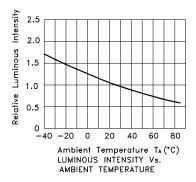
Super Bright Green

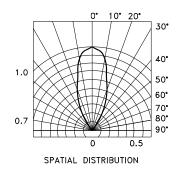
AM27SGD03









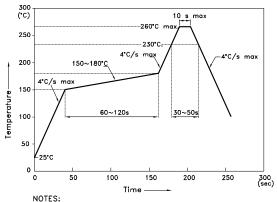


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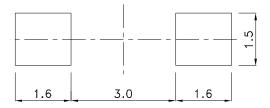
Reflow Soldering Profile For Lead-free SMT Process.



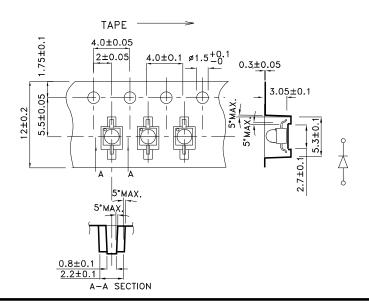
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Specifications (Units: mm)

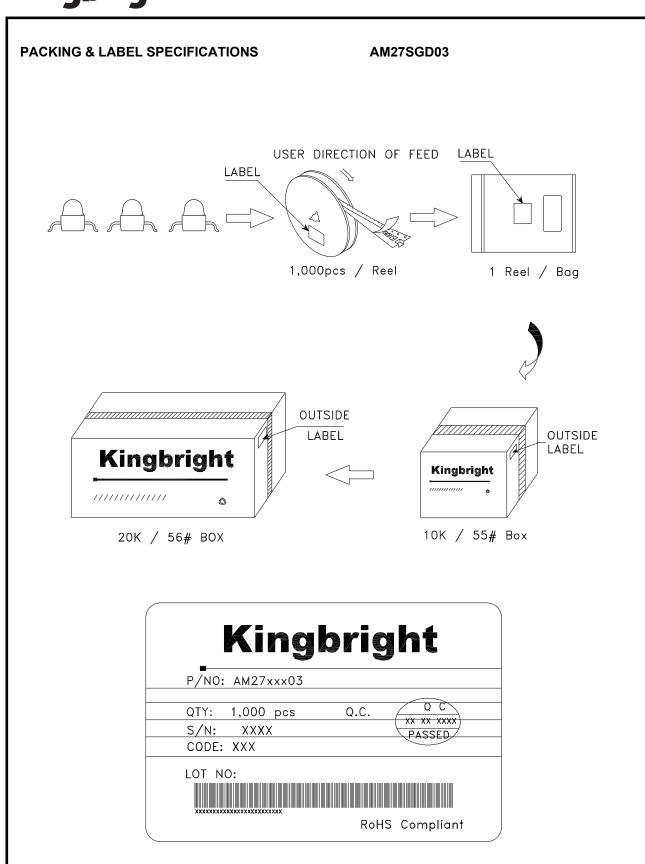


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